



WP 12 Thin Films

L.Tian, M. Benz, A. Mantoux, E. Blanquet, C. Jiménez, F. Weiss
SIMaP/LMGP (Grenoble INP)

Liang.Tian@simap.grenoble-inp.fr

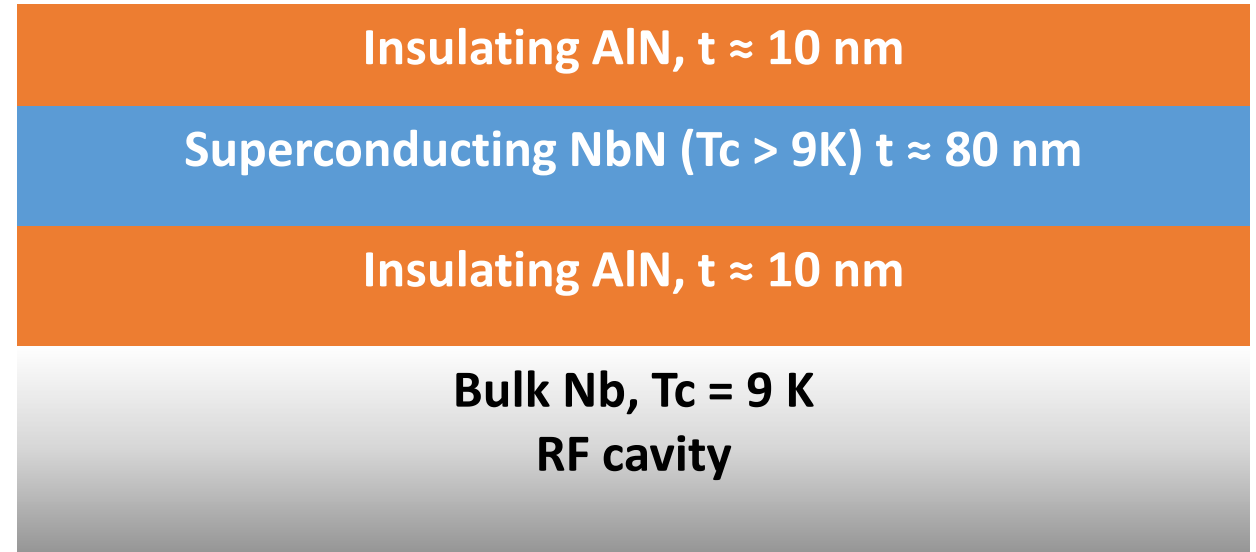
- Introduction
- ALD technique
- AlN deposition
- NbN deposition
- Multilayer deposition
- Conclusions and future work

Introduction

RF cavities: **bulk niobium**



Functionnal coating
(inside the cavity)

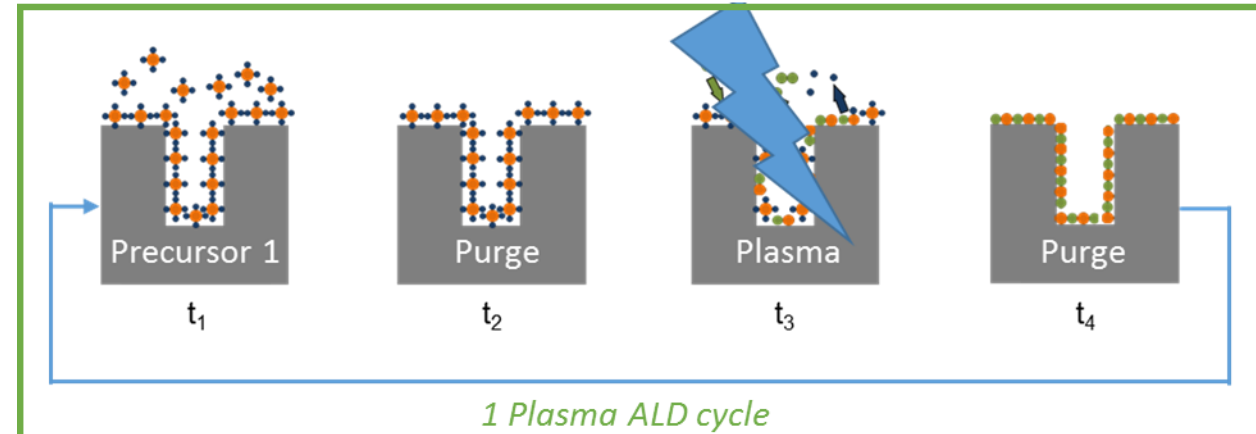
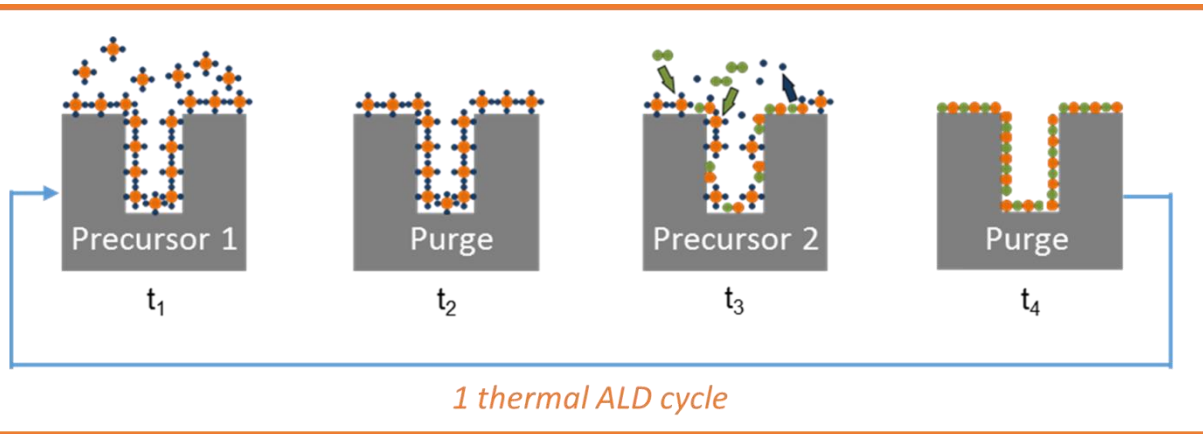


→ **Enhancement of the quality factor** and reduction of the electromagnetic loss

A. Gurevich, "Enhancement of RF breakdown field of SC by multilayer coating". *Appl. Phys.Lett.*, 2006. **88**

Challenge : conformal deposition on complex shape → **Atomic Layer Deposition**

ALD technique



- Higher reactivity, lower deposition temperature than ALD 😊
- Slightly less conformal than thermal ALD 😞

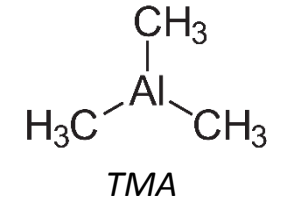
- **Sequential** introduction of the precursors, surface **saturation** : **conformal process**
- Mono-atomic layers (ideally in the « **ALD window** »)

AlN deposition

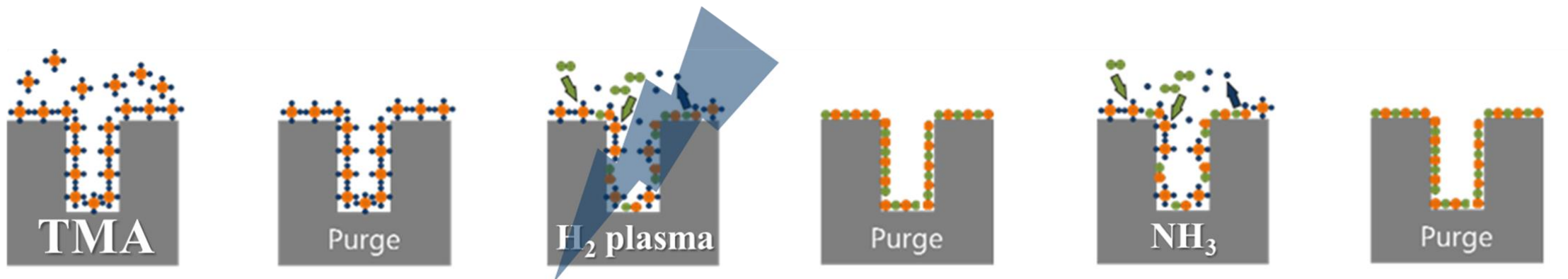
- Thermal ALD issue :
 - NH₃ reactive above 350°C
 - TMA decomposition above 375°C



- Most common settings in plasma ALD* :
 - Al source : TMA
 - N source : NH₃ **plasma**
 - Temperature : 350°C

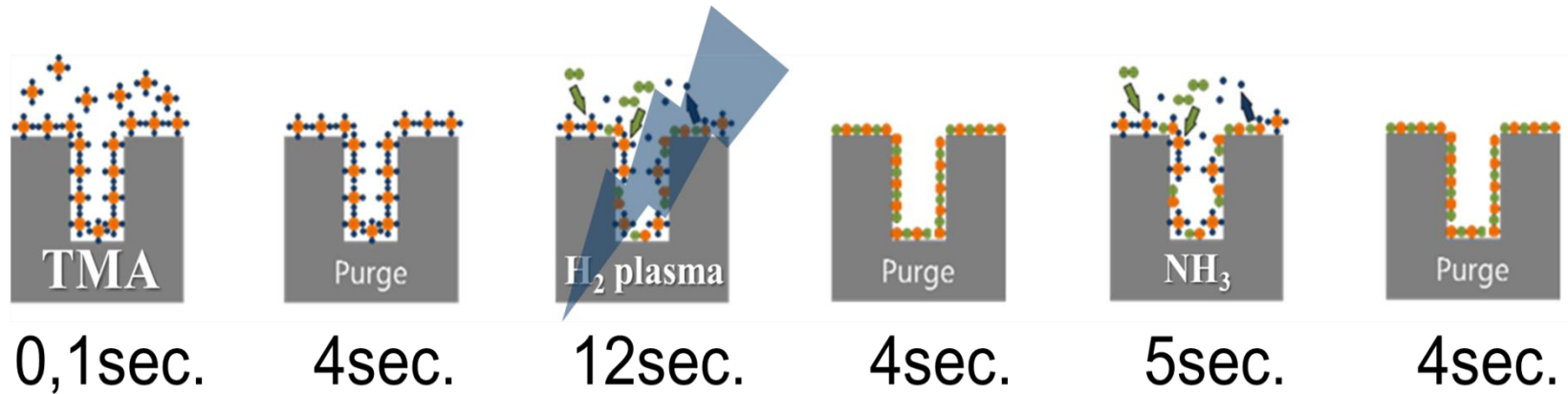


New deposition strategy : use of a hydrogen plasma for precursor reduction



AlN deposition

PEALD : plasma enhanced atomic layer deposition
= classic ALD with two more steps → 6 times cycles
→ **Supercycle**



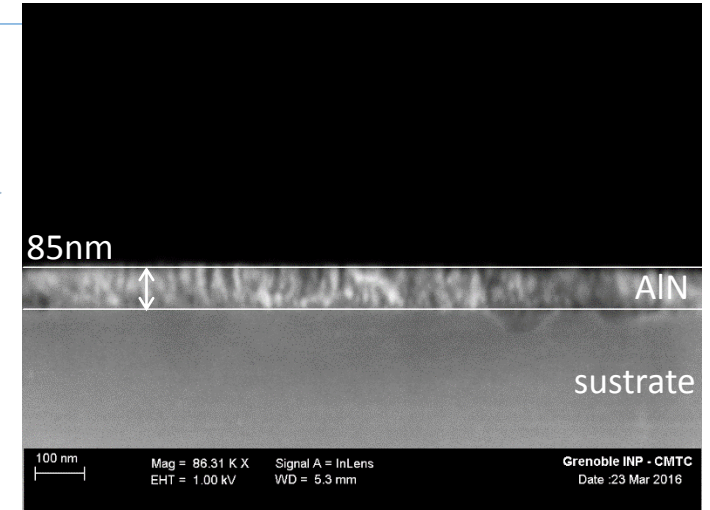
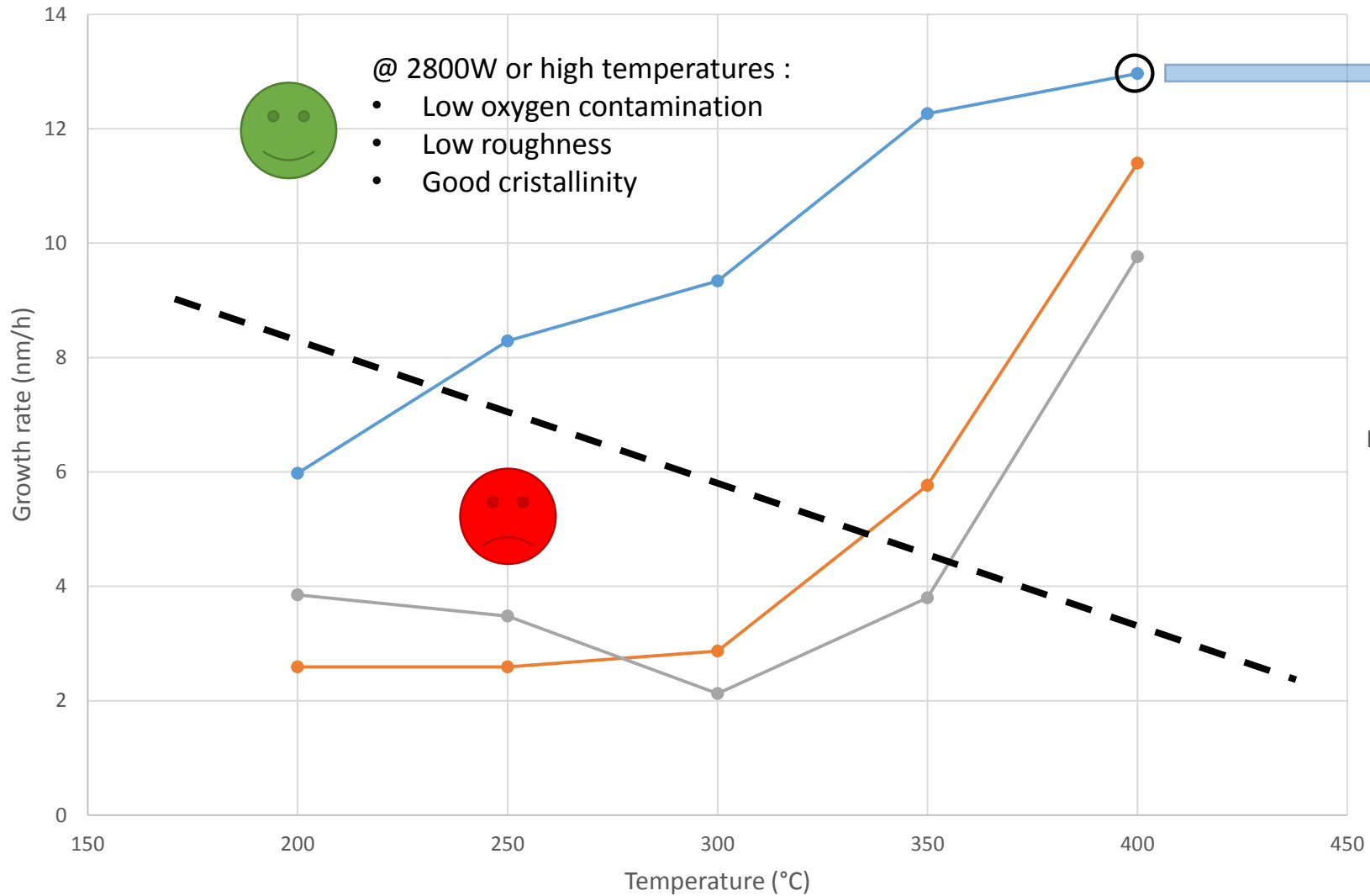
- Constant parameters :
 - 1000 cycles
 - 8 hPa in pressure
 - Pulses time

- Studied parameters :
 - Temperature
 - Plasma power



AlN deposition

PEALD (TMA/H₂ plasma/NH₃), 1000 cycles



Plasma power :

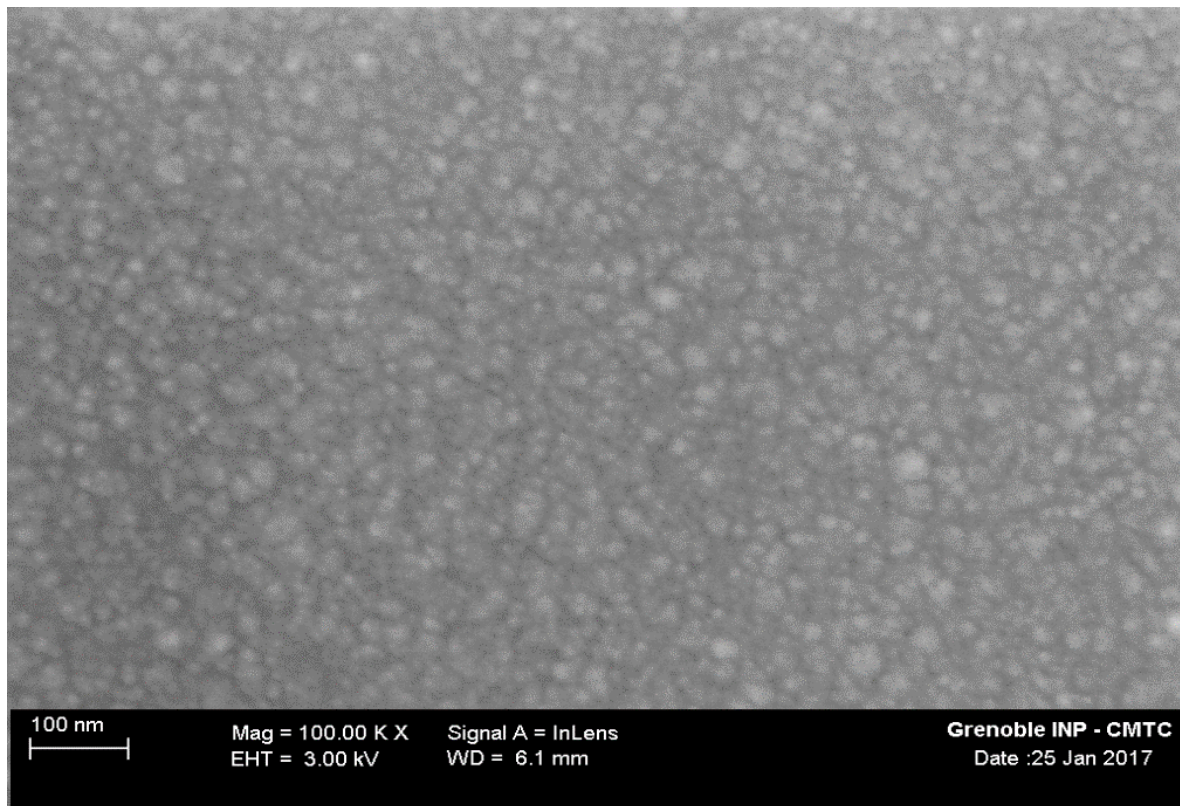
- 2800W
- 1000W
- 500W

Good processing conditions

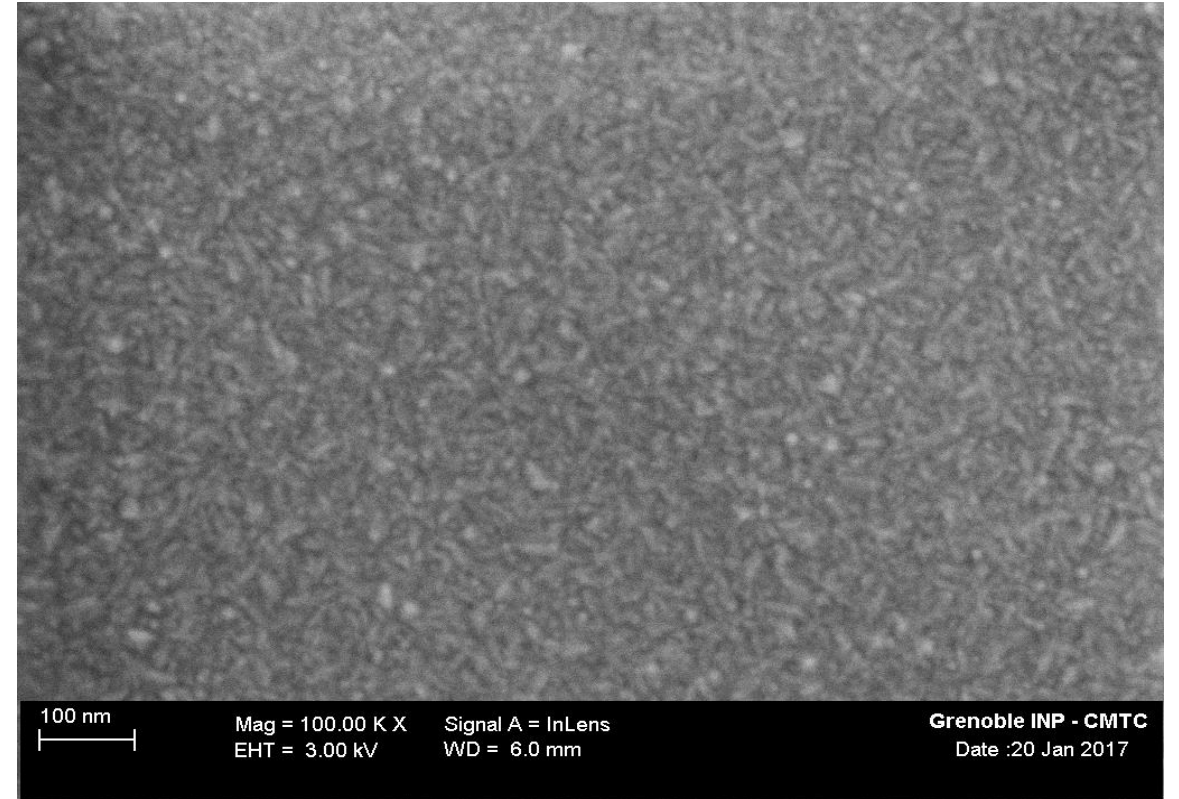
- Above 400°C @ 500W
- Above 350°C @ 1000W
- Above 250°C @ 2800W

AlN - SEM images

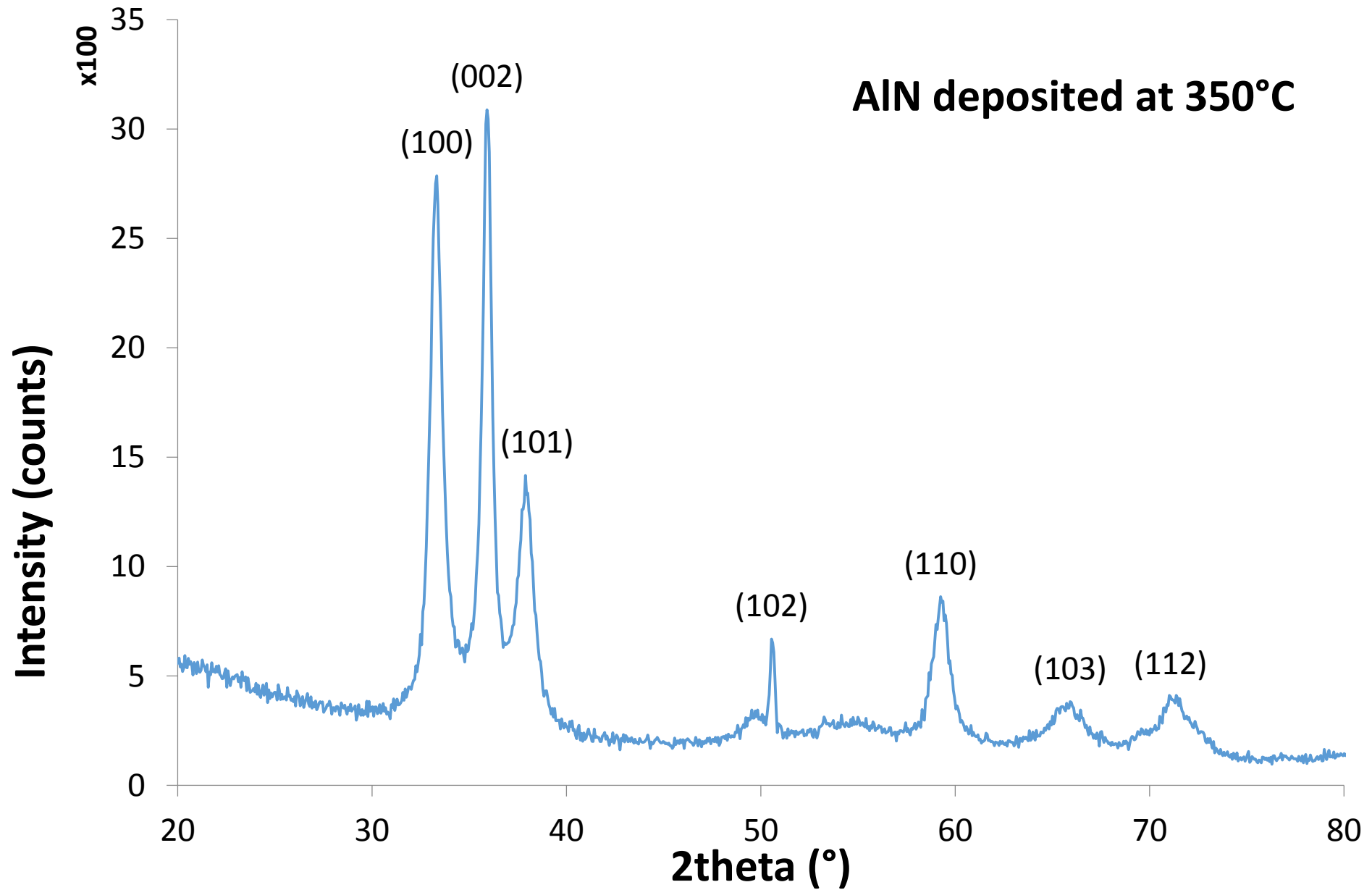
AlN deposited at 350 °C (90 nm thick)



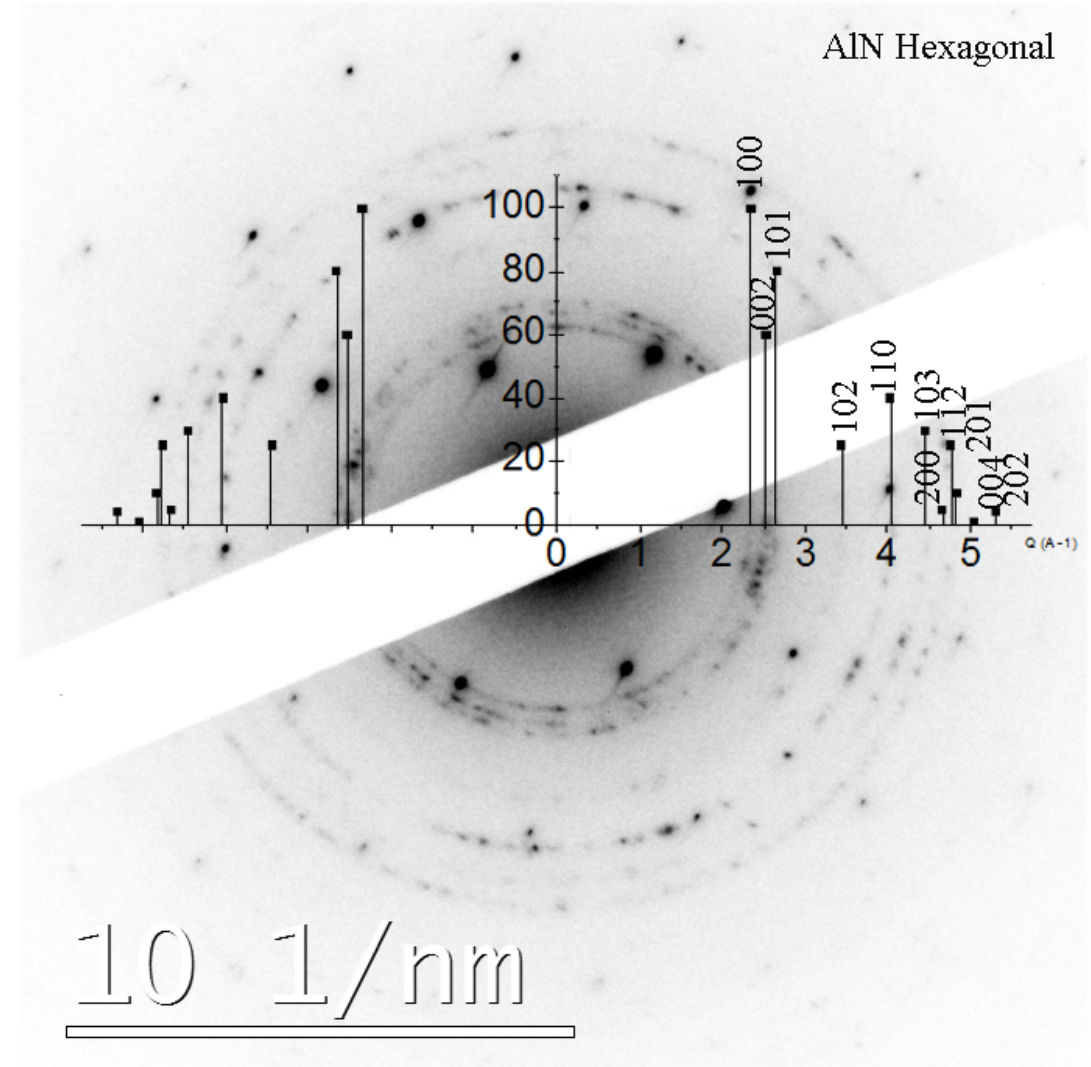
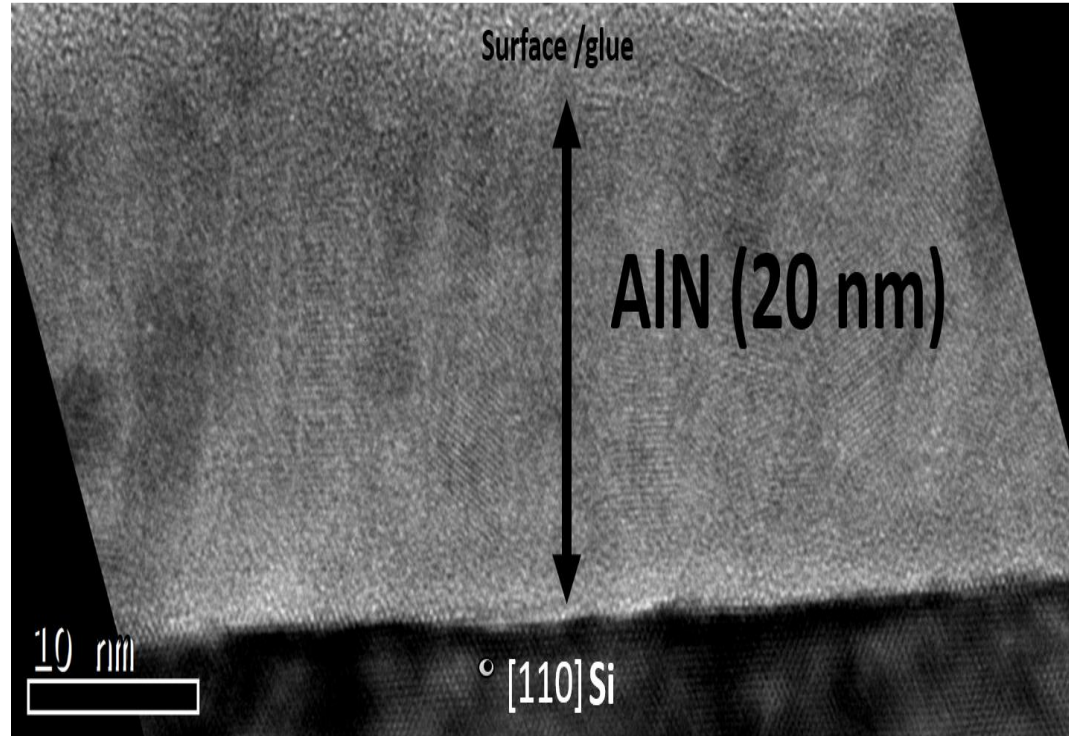
AlN deposited at 400 °C (90 nm thick)



AlN - XRD



TEM



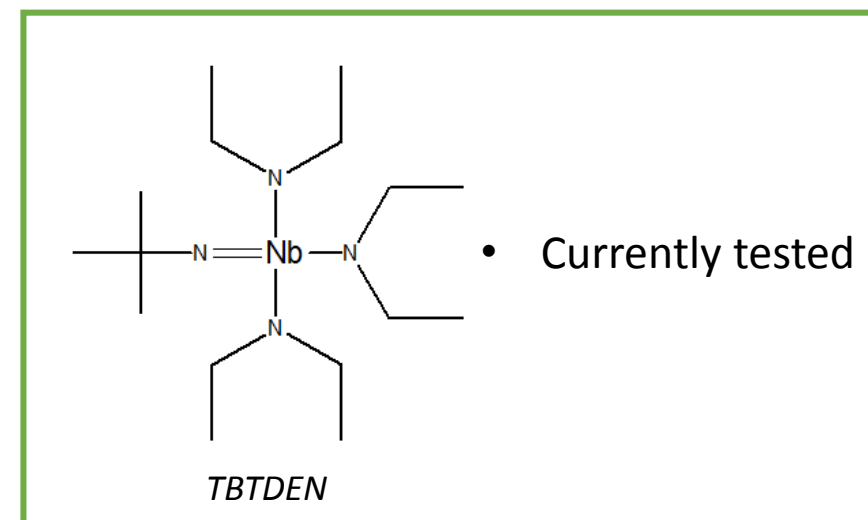
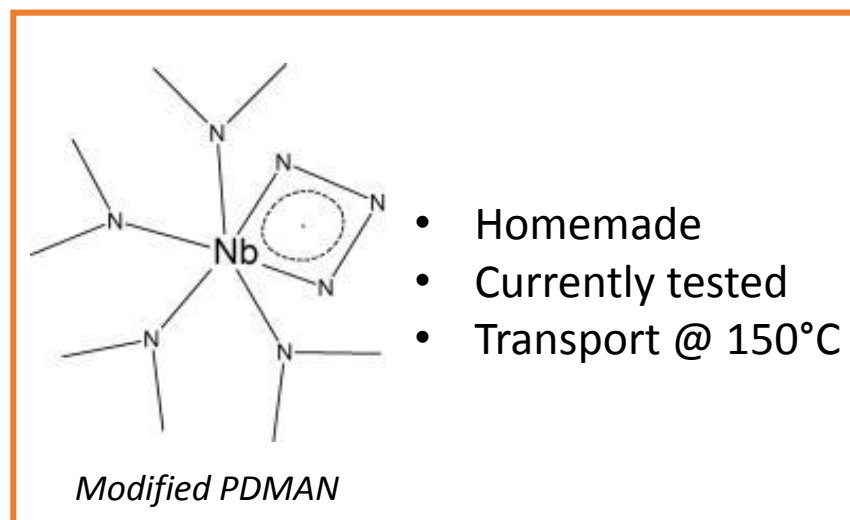
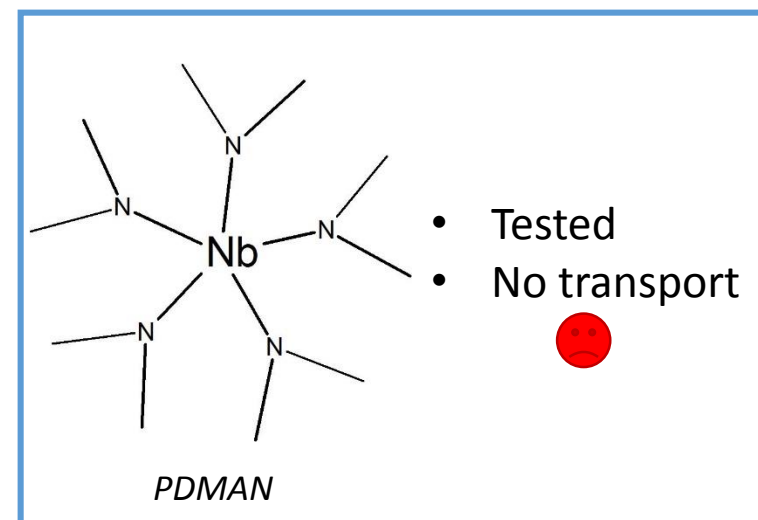
Summary on AlN depositions

- **AlN has been successfully optimised with the following growth conditions:**

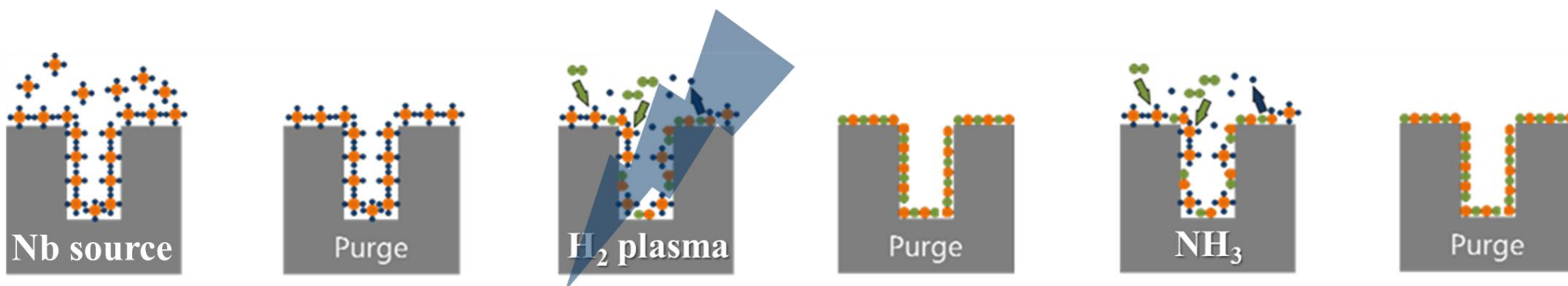
precursor TMA (20 °C)

growth temperature : 350 °C

plasma power: 2800 W

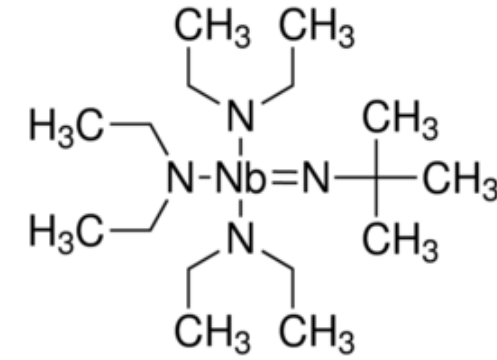
*Niobium nitride deposition*

General strategy : niobium reduction Nb^{V} (precursor) \rightarrow Nb^{III} (NbN)



NbN thin films

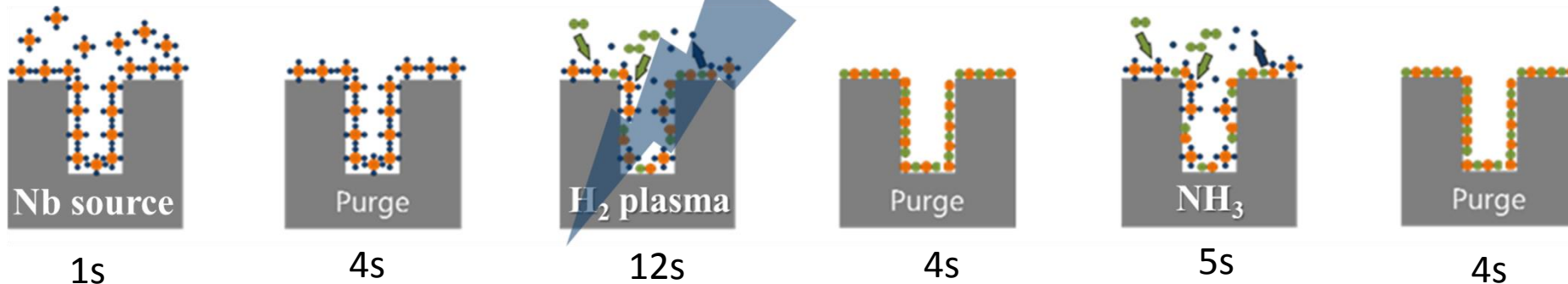
Metallic precursor Nb^{+V} : TBTDEN



General strategy : niobium reduction **Nb^V** (precursor) → **Nb^{III}** (NbN)

SuperCycle NbN

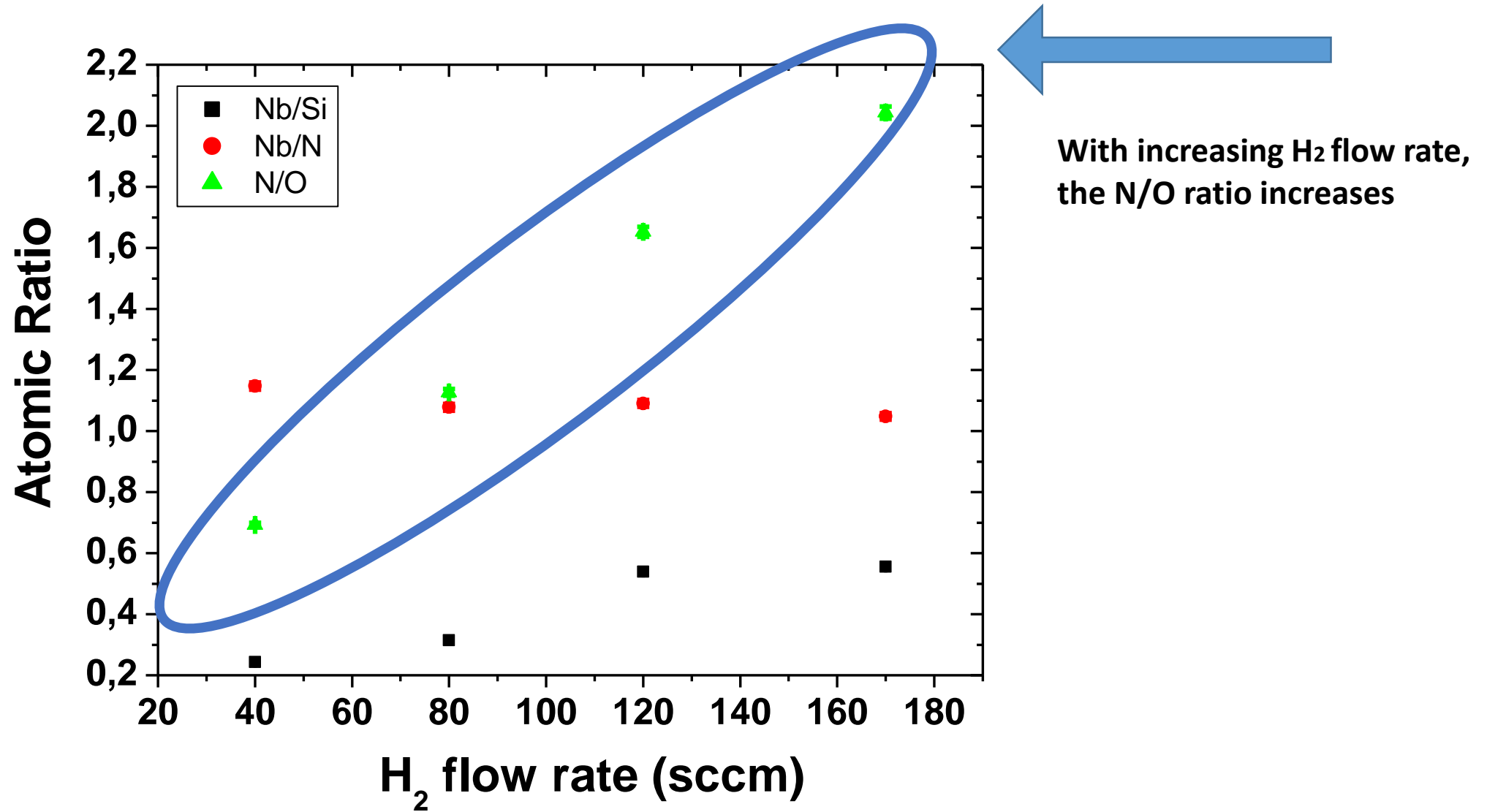
TBTDEN 1s / Purge 4s / H₂ plasma 12s / Purge 4s / NH₃ 5s / Purge 4s



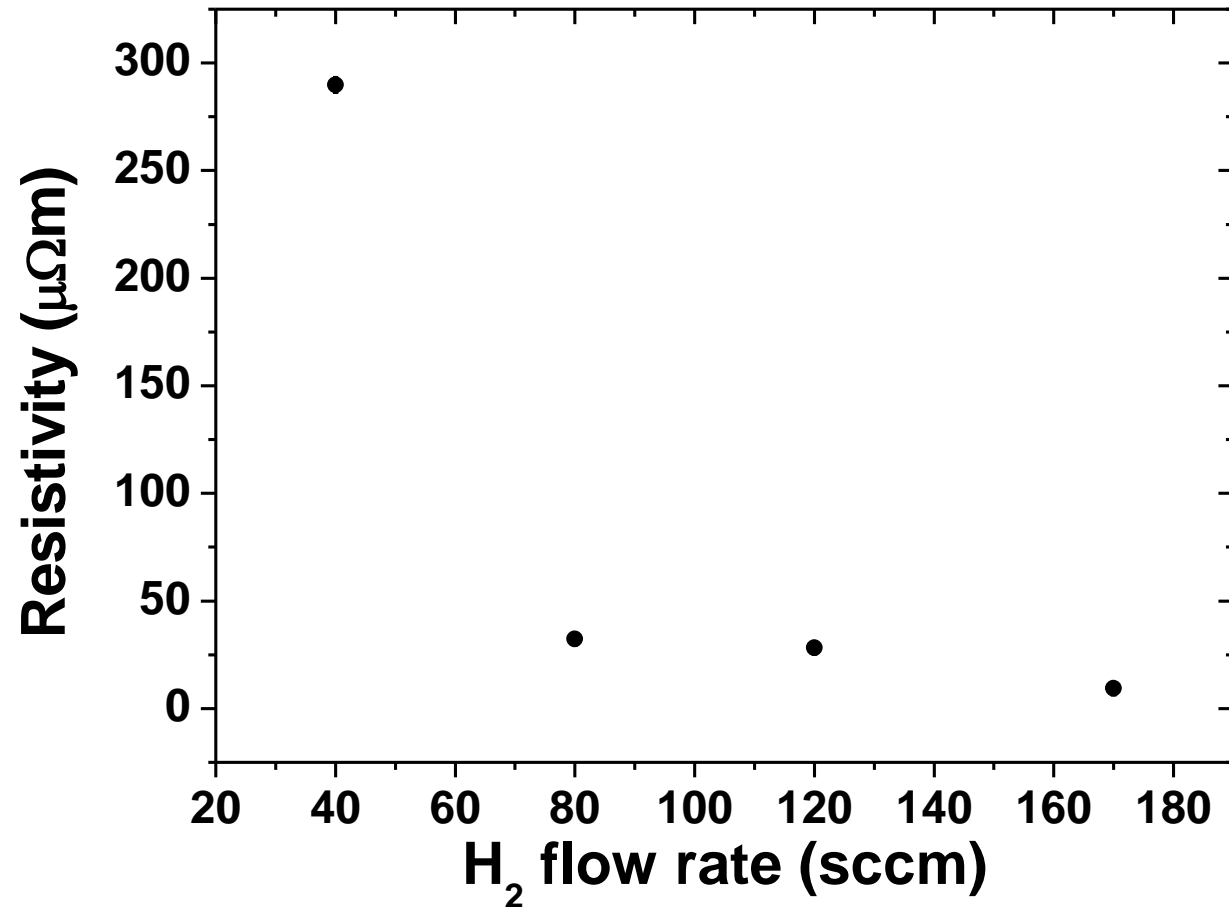
NbN thin films deposited as a function of H₂ flow rate

Sample No.	Growth conditions	Thickness
NbN7	350 °C; 2000 cycle; plasma:2.8 kW, 40sccm, 40hpa	60 nm
NbN8	350 °C; 2000 cycle; plasma:2.8 kW, 80 sccm, 40 hpa	60 nm
NbN9	350 °C; 2000 cycle; plasma:2.8 kW, 120 sccm, 40 hpa	60 nm
NbN10	350 °C; 2000 cycle; plasma:2.8 kW, 170 sccm, 40 hpa	60 nm

NbN- EDX



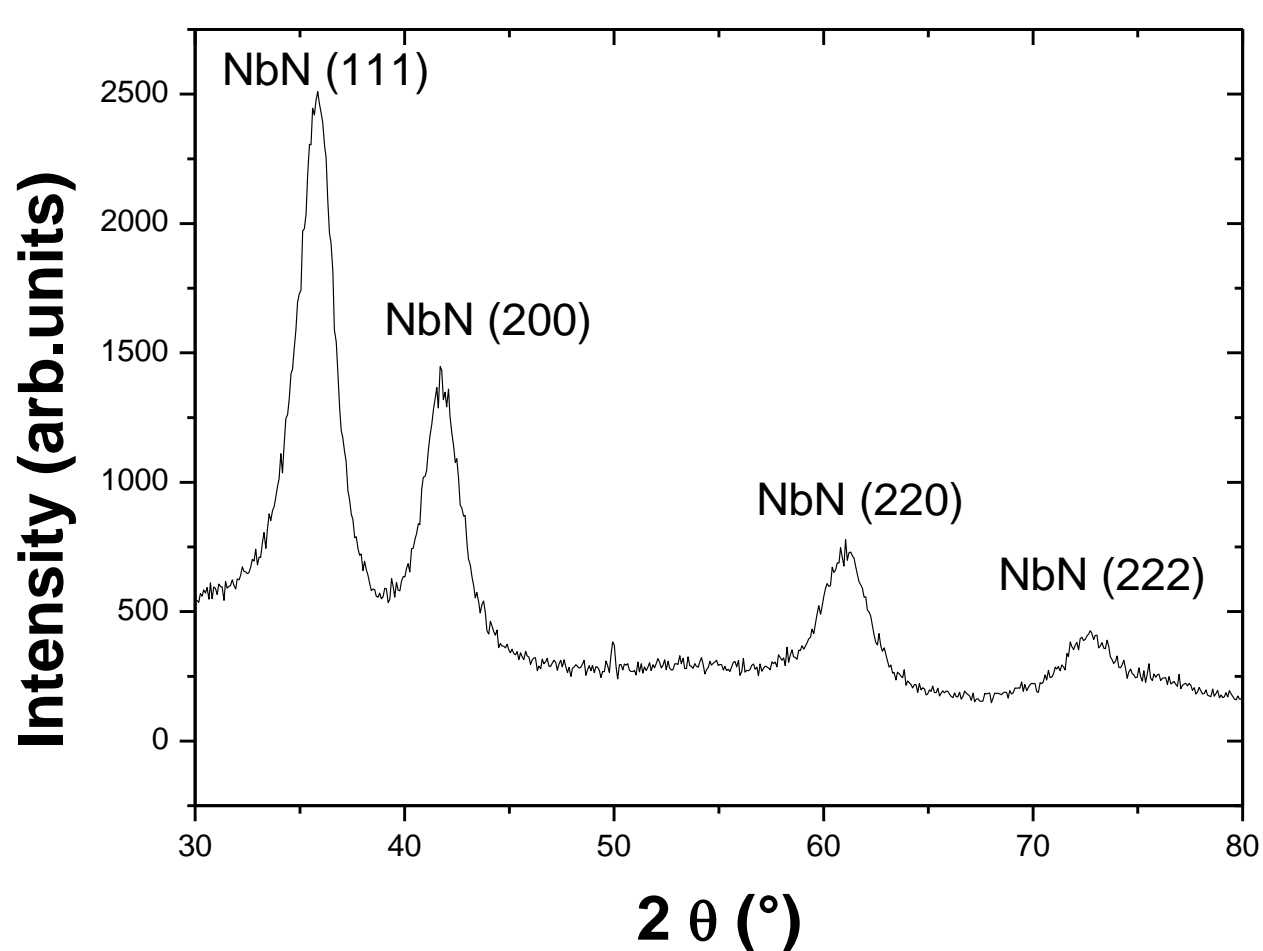
NbN- Resistivity



H ₂ flow rate	Resistivity (μΩm)
40 sccm	289,75±3
80 sccm	32,3±0,3
120 sccm	28,20±0,3
170 sccm	9,38±0,1

Resistivities were measured by Van der Pauw measurements at room temperature

NbN - XRD

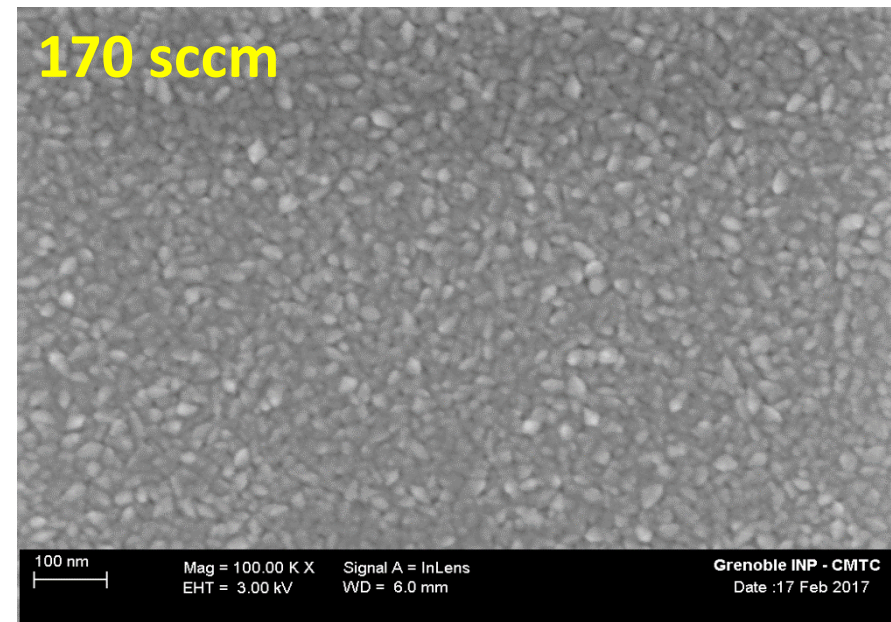
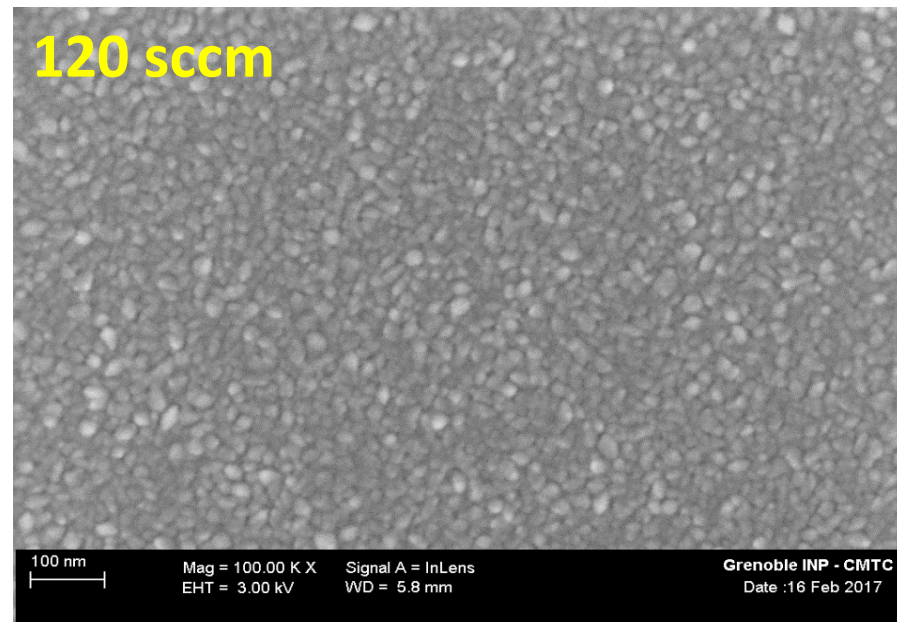
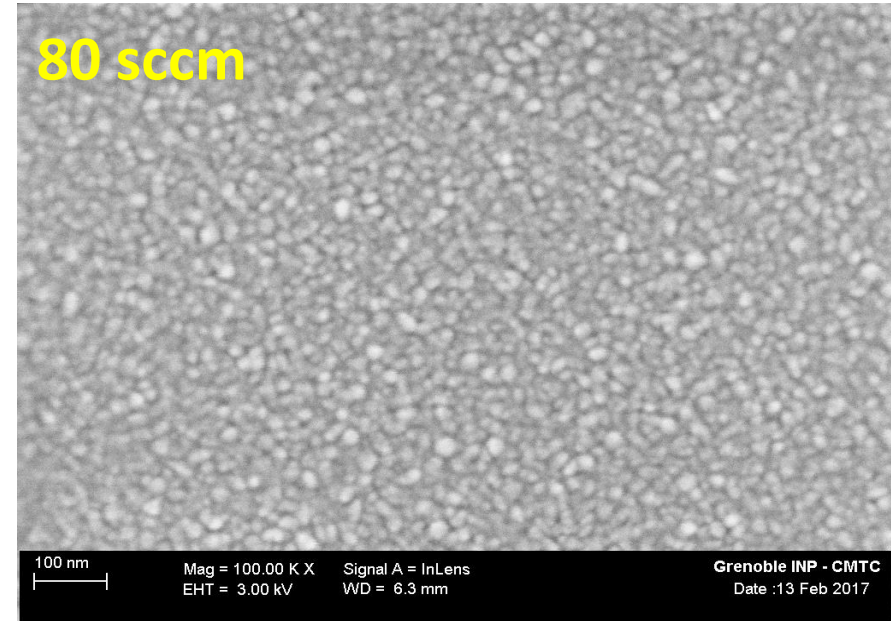
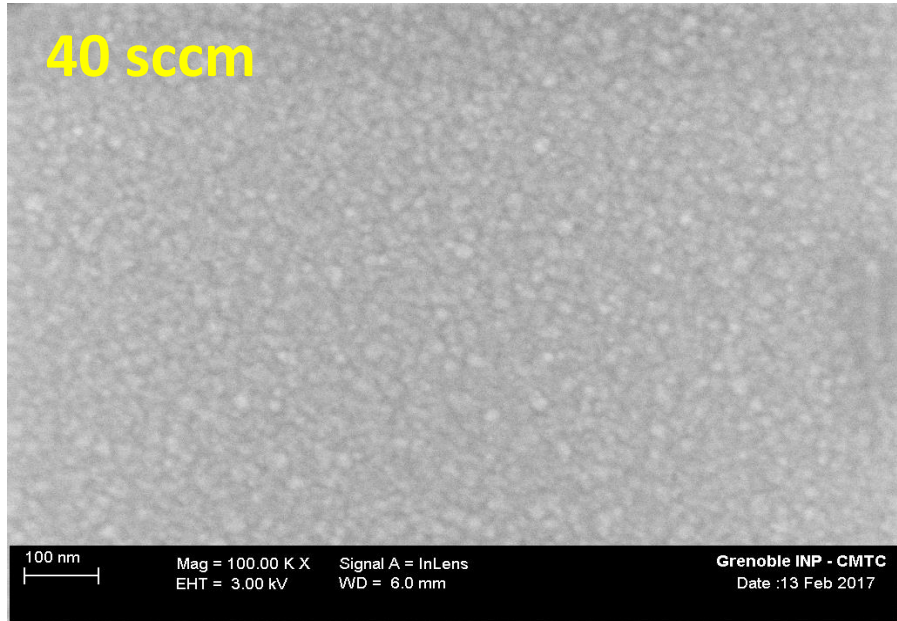


NbN Cubic δ phase

Calculated lattice parameter: $a = 0.4335$ nm

Reference: bulk NbN $a = 0.439$ nm

NbN - SEM



T_c measurement : not superconducting yet

TEM of NbN is ongoing at LMGP

Summary on NbN

- The best NbN sample was deposited with precursor TBTDEN
Substrate temperature 240 °C
Plasma power 2000 W
Growth rate 2.2 nm/h
- GIXRD result showed NbN cubic δ phase, no indication of niobium oxide crystallites

AlN/NbN multilayers

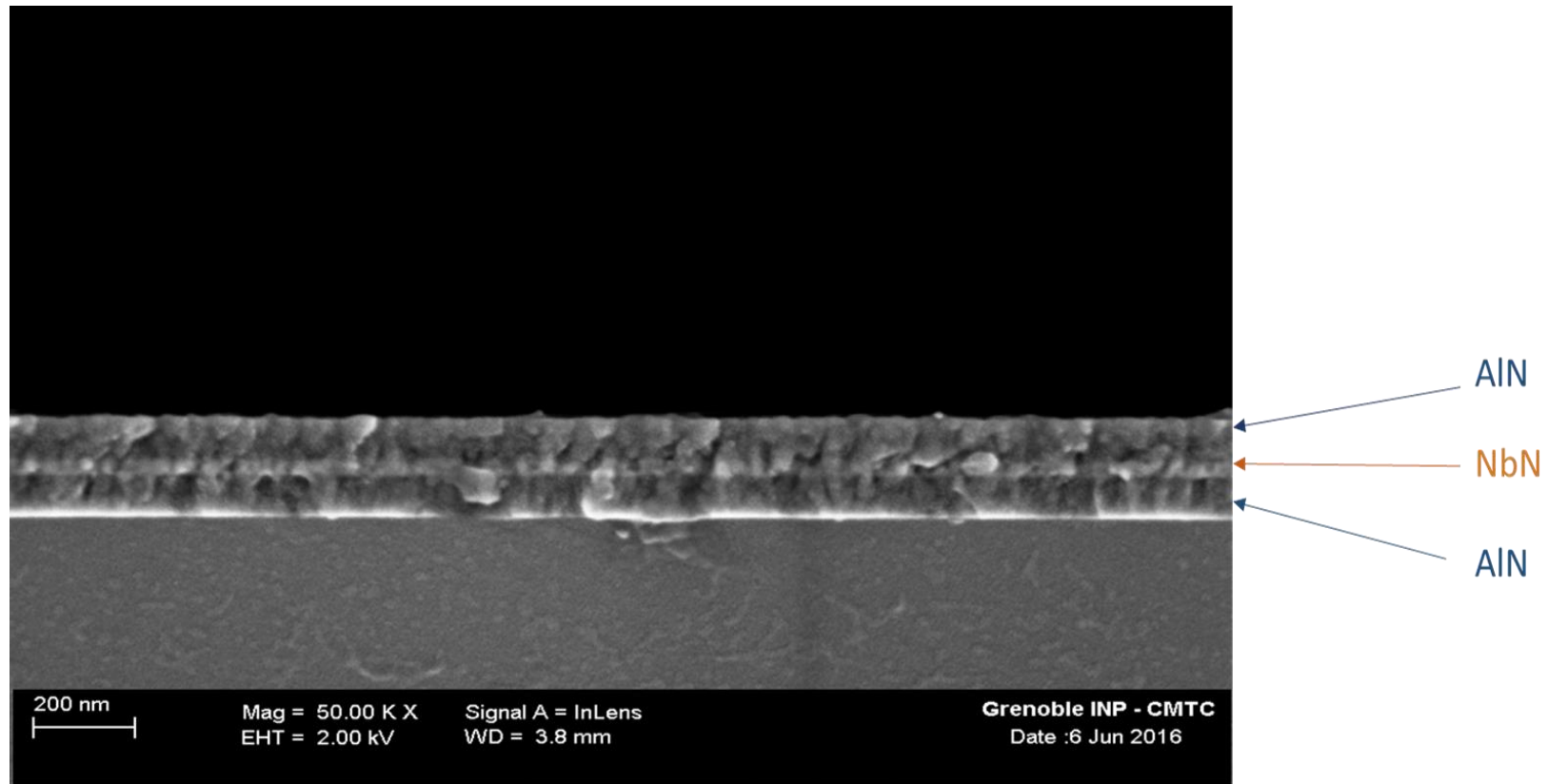
SuperCycle AlN à 350°C

TMA 0,1s / Purge 4s / H₂ plasma 12s / Purge 4s / NH₃ 5s / Purge 4s

SuperCycle NbN à 240°C

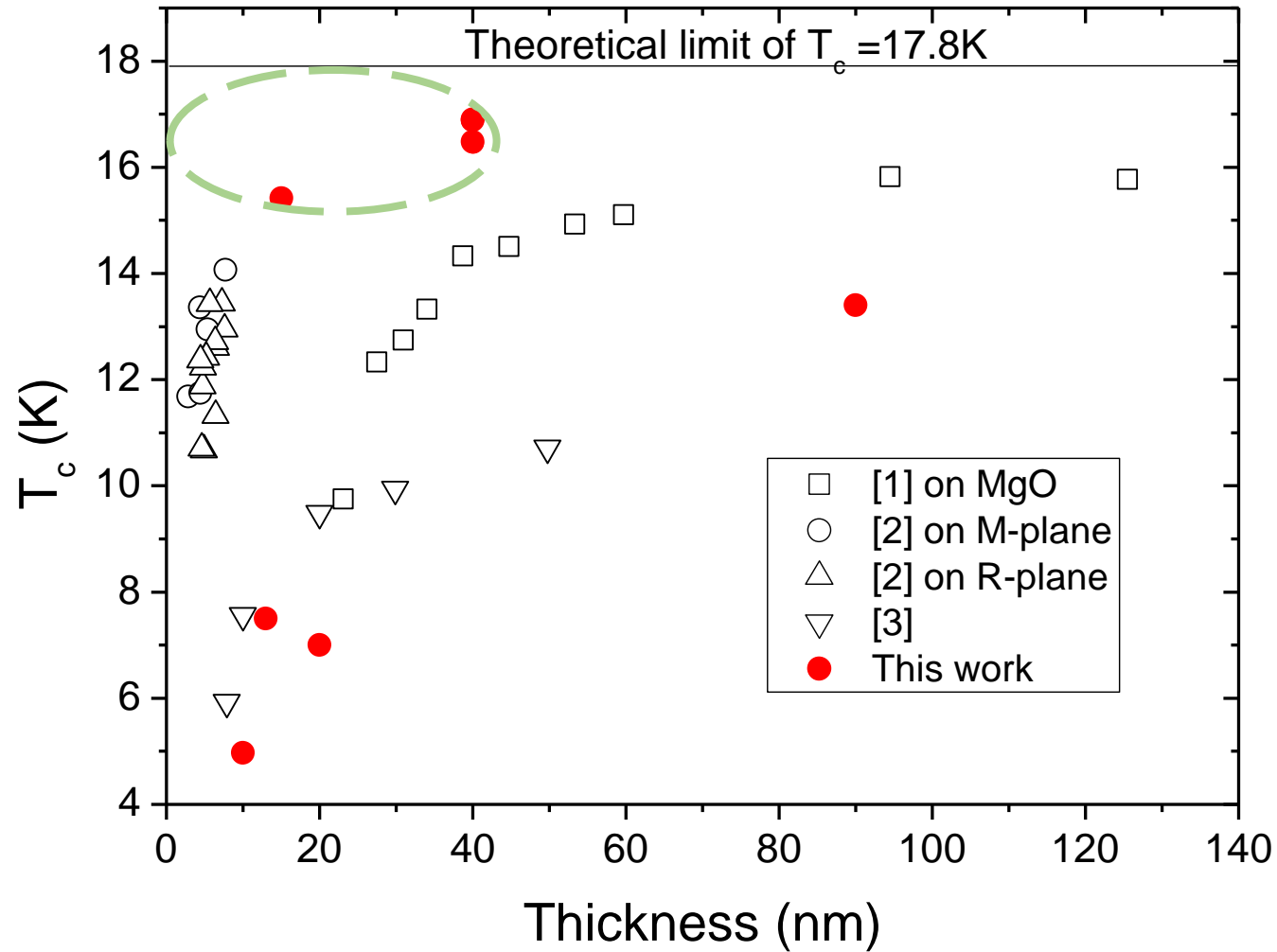
TBTDEN 1s / Purge 4s / H₂ plasma 12s / Purge 4s / NH₃ 5s / Purge 4s

AlN/NbN multilayers



IB-NbN-12 260°C (NbN)

Superconducting properties



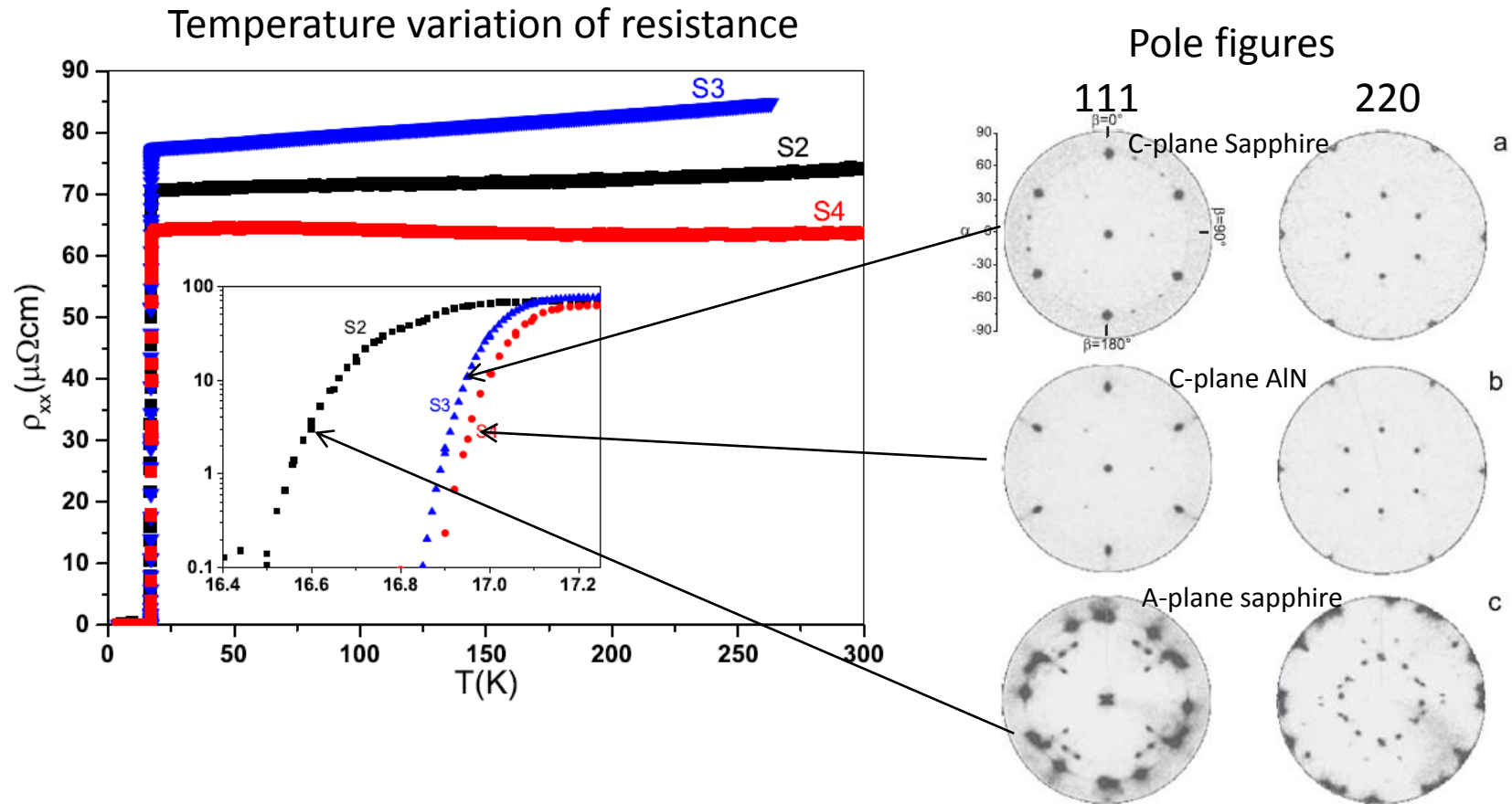
- [1] Miki et al. Applied Physics Express 2 (2009) 075002
- [2] Villegier et al. APL 2009
- [3] Shiino et al. Supercond. Sci. Technol. 23 (2010) 045004

Highest T_c reported so far (17.06K) for NbN together with low resistivity value ($50 \mu\Omega\text{cm}$)

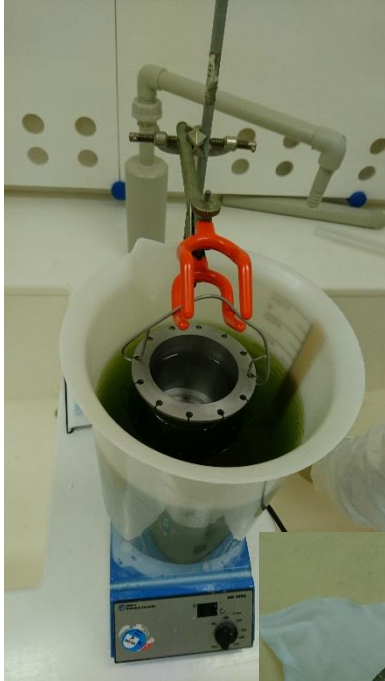
NbTiN/NbN multilayers by CVD

Crystalline quality vs electrical transport

Electrical transport measurements performed down to 4 K in a PPMS.
Same growth conditions, different substrates



CVD deposition of ML on HZB cavities



- Nb samples from the HZB cavities treated (BCP + heat treatment at Saclay) and sent to Grenoble
- Will be deposited with AlN/NbN layers by CVD and/or ALD
- Will be tested back at Saclay (small sample, magnetometry) and HZB (RF) mid-2017

Conclusions and Future work

- PEALD of AlN has been optimized
- PEALD of NbN has the expected cubic δ phase
- High quality NbN obtained by CVD (guideline for ALD)

Future work

- Development of the ALD process to get SC NbN
- AlN/NbN/AlN multilayers will be grown with various thickness combinations and will be characterized